

Ver.1.0

Diagonal 6.43 mm (Type 1/2.8) CMOS Solid-state Image Sensor with Square Pixel for Color Cameras

Description

The IMX515-AAQN is a diagonal 6.4 mm (Type 1/2.8) CMOS active pixel type solid-state image sensor with a square pixel array and 8.46 M effective pixels. This chip operates with analog 2.9 V, digital 1.1 V, and interface 1.8 V triple power supply, and has low power consumption. High sensitivity, low dark current and no smear are achieved through the adoption of R, G and B primary color mosaic filters. This chip features an electronic shutter with variable charge-integration time.

(Applications: Security cameras, FA cameras, Industrial cameras)

Features

- ◆ CMOS active pixel type dots
- ◆ Built-in timing adjustment circuit, H/V driver and serial communication circuit
- ◆ Input frequency: 24 MHz / 27 MHz / 37.125 MHz / 72 MHz / 74.25 MHz
- ◆ Number of recommended recording pixels: 3840 (H) × 2160 (V) approx. 8.29 M pixels
- ◆ Readout mode
 - All-pixel scan mode
 - Horizontal / Vertical 2/2-line binning mode
 - Window cropping mode
 - Horizontal / Vertical direction - Normal / Inverted readout mode
- ◆ Readout rate
 - Maximum frame rate in
 - All-pixel scan mode: 12 bit: 52.2 frame/s, 10 bit: 61.6 frame/s
- ◆ High dynamic range (HDR) function
 - Multiple exposure HDR
 - Digital overlap HDR
- ◆ Synchronizing sensors function
- ◆ Variable-speed shutter function (resolution 1H units)
- ◆ CDS / PGA function
 - 0 dB to 30 dB : Analog Gain 30 dB (step pitch 0.3 dB)
 - 30.3 dB to 72 dB : Analog Gain 30 dB + Digital Gain 0.3 dB to 42 dB (step pitch 0.3 dB)
- ◆ Supports I/O
 - CSI-2 serial data output (2 Lane / 4 Lane), RAW10 / RAW12 output

STARVIS

* STARVIS is a registered trademark or trademark of Sony Group Corporation or its affiliates. The STARVIS is back-illuminated pixel technology used in CMOS image sensors for security camera applications. It features a sensitivity of 2000 mV or more per $1\ \mu\text{m}^2$ (color product, when imaging with a $706\ \text{cd}/\text{m}^2$ light source, F5.6 in 1 s accumulation equivalent), and realizes high picture quality in the visible-light and near infrared light regions.

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Device Structure

- ◆ CMOS image sensor
- ◆ Image size Diagonal 6.4 mm (Type 1/2.8) approx. 8.40 M pixels, All pixels
- ◆ Total number of pixels 3864 (H) × 2228 (V) approx. 8.60 M pixels
- ◆ Number of effective pixels 3864 (H) × 2192 (V) approx. 8.46 M pixels
- ◆ Number of active pixels 3864 (H) × 2176 (V) approx. 8.40 M pixels
- ◆ Number of recommended recording pixels 3840 (H) × 2160 (V) approx. 8.29 M pixels
- ◆ Unit cell size 1.45 μm (H) × 1.45 μm (V)
- ◆ Optical black
Horizontal (H) direction: Front 0 pixel, rear 0 pixel
Vertical (V) direction: Front 36 pixels, rear 0 pixel
- ◆ Dummy
Horizontal (H) direction: Front 0 pixel, rear 0 pixel
Vertical (V) direction: Front 1 pixel, rear 1 pixel
- ◆ Package 65 pin BGA

Image Sensor Characteristics

(Tj = 60 °C)

Item		Value	Remarks
Sensitivity (F5.6)	Typ.	5640 Digit/lx/s	12 bit converted value
Saturation signal	Min.	3895 Digit	12 bit converted value

Basic Drive Mode

Drive mode	Recommended number of recording pixels	Maximum frame rate [frame/s]	Output interface	ADC [bit]
All pixel	3840 (H) × 2160 (V) approx. 8.29 M pixels	61.6	CSI-2	10
Horizontal/ Vertical 2/2-line binning	1920 (H) × 1080 (V) approx. 2.07 M pixels	88.1	CSI-2	10

